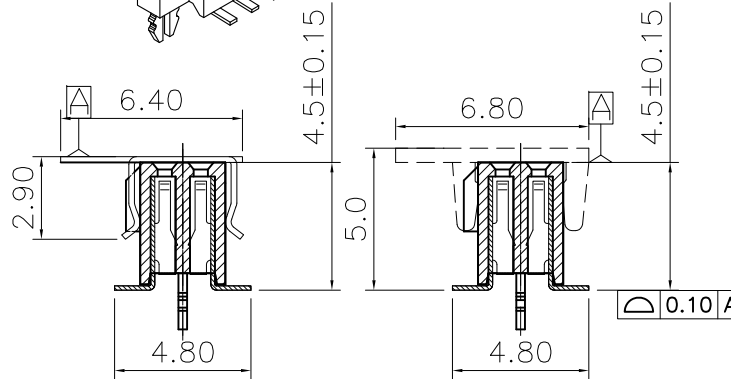
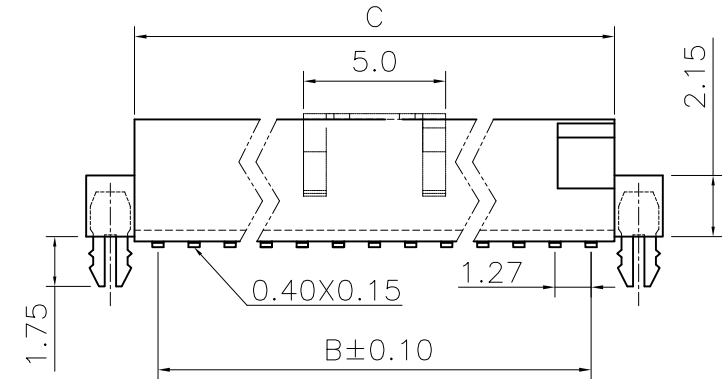
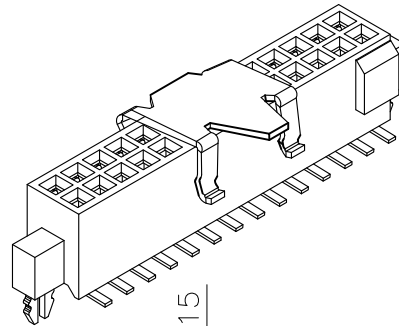
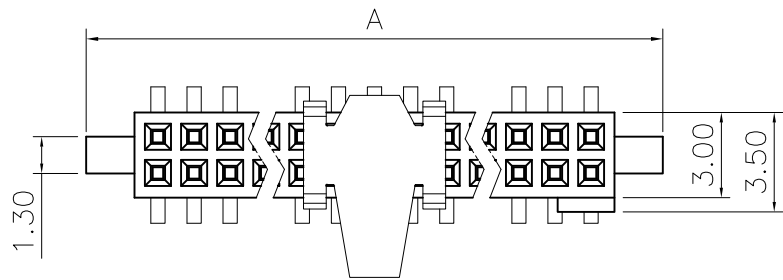
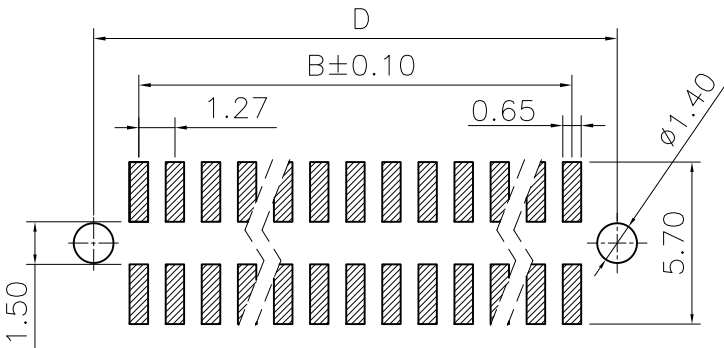


REV.	SPECIFICATION	ECN NO.	APPD.
R8		ECN220843	



M: Metal Pad

P: Plastic Pad



P.C. Board Layout
(Tolerance:±0.05mm)

2243- xx C xx D L x -X
 Series ——— xx ——— C ——— xx ——— D ——— L ——— x ——— -X
 No. of Position ———
 C: Selective ———
 Gold Plated ———
 G: Gold Plated ———
 00: G/F ———
 10: 10 μ" ———
 15: 15 μ" ———
 30: 30 μ" ———
 P: Plastic Pad ———
 M: Metal Pad ———
 U: Tube Pad ———
 T: Tape&Reel Package ———
 L: With Board Lock ———
 D: Surface Mount ———

Material and Plating:

Housing: LCP, UL94V-0, Black.

Contacts: Phosphor Bronze.

Lock: Phosphor Bronze.

Gold Plated on Contact Area and 80u"Min Tin Plated or Gold Flash on Solder Tail over Nickel 50u" Min.

Electrical Characteristics:

Current Rating: 1 AMP.

Dielectric Withstanding Voltage: AC 500V For 1 minute.

Insulator Resistance: 1000MΩ min. at DC 500V.

Contact Resistance: 20mΩ max. at DC 100mA.

Operating Temperature: -65°C ~ +125°C.

***RoHS Compliant**

Insertion Depth: 1.90mm to 2.90mm

Position	14 Thru 100
Dimension	
A	1.27 X No. of Positions/2 +3.78
B	1.27 X No. of Positions/2 -1.27
C	1.27 X No. of Positions/2 +0.38
D	1.27 X No. of Positions/2 +1.91

Tolerances	Dwg. No.	2243D02012	Title:
x = ±0.5	Projection		2243 Series
.x = ±0.25	Unit	mm	P.C.B. Socket
.xx = ±0.15	Scale	1:1	1.27mmX1.27mm
	Drawn By	CCH8/22/22	

OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 2243-xxCxxDLx-X			
SHEET	1/1	Ver. No.	R8